

ABSTRACT OF THE DISCLOSURE

The invention enhances the reliability of a semiconductor device. A semiconductor device includes: a semiconductor substrate that includes an active element region, an integrated circuit having an active element in the active element region, and an electrode electrically connected to the integrated circuit; a resin layer that is formed on the surface of the semiconductor substrate where the electrode is also formed, so as to avoid the electrode; a wiring layer that extends from the electrode and across the top of the resin layer, and includes a plurality of electrically connecting portions; and an external terminal that is provided on the electrically connecting portions. The plurality of electrically connecting portions includes a first electrically connecting portion and a second electrically connecting portion. The surface area of the first electrically connecting portion is larger than the surface area of the second electrically connecting portion.